



SOD123FL Rectifier

Material Content Declaration					
Material name	Substance name e.g. Copper (Cu).	CAS no., if known	Substance mass (mg)	% OF Weight (%)	PPM Of Total Weight
Lead Frame 28.52%	Copper (Cu)	7440-50-8	4.34830	99.9609	285134.4
	Sulfur (S)	7704-34-9	0.00100	0.0230	65.6
	Arsenic (As)	7440-38-2	0.00008	0.0018	5.2
	Tin (Sn)	7440-31-5	0.00008	0.0018	5.2
	Oxygen (O)	7782-44-7	0.00004	0.0009	2.6
	Phosphorus (P)	7723-14-0	0.00007	0.0016	4.6
	Iron (Fe)	7439-89-6	0.00005	0.0011	3.3
	Nickel (Ni)	7440-02-0	0.00002	0.0005	1.3
	Bismuth (Bi)	7440-69-9	0.00015	0.0034	9.8
	Antimony (Sb)	1309-64-4	0.00016	0.0037	10.5
	Lead (Pb)	7439-92-1	0.00003	0.0007	2.0
	Zinc (Zn)	7440-66-6	0.00002	0.0005	1.3
	Total			4.35	
Solder Wafer 7.21%	Lead (Pb)	7439-92-1	1.018	92.50	66,721.3
	Tin (Sn)	7440-31-5	0.055	5.00	3606.6
	Silver (Ag)	7440-22-4	0.028	2.50	1803.3
	Total			1.10	
Chip 3.93%	Silicon (Si)	7440-21-3	0.572	95.40	37,534.4
	Lead (Pb)	7439-92-1	0.028	4.60	1,809.8
	Total			0.60	
Molding 51.68%	Silica (SiO2)	14808-60-7	5.840	74.11	382,942.2
	Epoxy resin	29690-82-2	1.340	17.00	87,842.6
	Phenolic resin	9003-35-4	0.693	8.80	45,471.5
	Phosphorus(P)	7723-14-0	0.004	0.05	258.4
	Carbon Black	1333-86-4	0.003	0.04	206.7
	Total			7.880	
Plating 8.66%	Tin (Sn)	7440-31-5	1.320	100.00	86,557.4
	Total			1.32	
	Total mass (mg)		15.25		